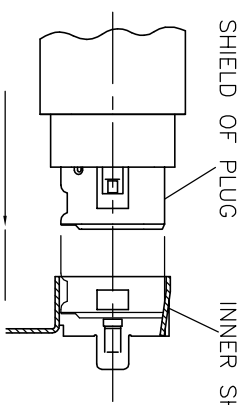
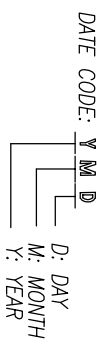


RECOMMENDED PCB LAYOUT
(TOP VIEW)(TOL. ±0.05) THK:1.2mm

SPECIFICATIONS:

1. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SE
2. MARKING: MARK "YMD" ON REAR OF CONNECTOR.
3. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
4. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
5. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
6. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
7. PRINTED DATE CODE "Y M D" ON TOP OF CONNECTOR.



A-A SECTION OF INNER SHIELD

REV.	EGN NO	OR DESCRIPTION	REVISED	DATE
A	PRODUCT	RELEASE	Stone	2018.08.13
B	ECR NO.	C202005-P01	HuangYu	2020.06.09
C	ECR NO.	C202010-R04	HuangYu	2020.11.23

E	CONTACT TERMINAL	4	PHOSPHOR BRONZE 0.3T	SILVER PLATING
D	OUTER SHIELD	1	C2680-H-T=0.4mm	NICKEL PLATING
C	INNER SHIELD	1	BRASS 0.4T	NICKEL PLATING
B	COVER	1	HIGH TEMP THERMOPLASTIC	BLACK COLOR
A	BODY	1	HIGH TEMP THERMOPLASTIC	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信登企業股份有限公司

DECIMALS:		ANGLES:	
X	:±0.5	X	:±2°
X.X	:±0.3	X.X	:±1°
X.XX	:±0.2		
TITLE		MINI DIN 4P	
DWN	Yu-Huang	PART NO.	2MJ-0402A1POF
CHKD	Stone-Zhu	SCALE	1:1
APVD	jin-deng	SIZE	A3
		SHEET	10F1
		REV.	C

CUSTOMER COPY

